

HOSTAFORM® C 9021 AW

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Chemical abbreviation according to ISO 1043-1: POM Molding compound ISO 29988- POM-K, M-GNS, 03-002 POM copolymer Injection molding type with special additive modified; good chemical resistance to solvents, fuel and strong alkalis as well as good hydrolysis resistance; high resistance to thermal and oxidative degradation; good wear properties and low coefficient of friction. UL-registration in natural and black and a thickness more than 1.5 mm as UL 94 HB. Burning rate ISO 3795 and FMVSS 302 < 100 mm/min for a thickness more than 1 mm. Ranges of applications: sliding parts for window lifter. UL = Underwriters Laboratories (USA) FMVSS = Federal Motor Vehicle Safety Standard (USA)

Product information

Resin Identification	POM	ISO 1043
Part Marking Code	>POM<	ISO 11469

Rheological properties

Melt volume-flow rate	8 cm ³ /10min	ISO 1133
Temperature	190 °C	
Load	2.16 kg	
Moulding shrinkage, parallel	2.1 ^[1] %	ISO 294-4, 2577
Moulding shrinkage, normal	1.9 ^[1] %	ISO 294-4, 2577
[1]: @ 195 °C		

Typical mechanical properties

Tensile modulus	2600 MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	58 MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	8 %	ISO 527-1/-2
Nominal strain at break	20 %	ISO 527-1/-2
Flexural modulus	2500 MPa	ISO 178
Tensile creep modulus, 1h	2300 MPa	ISO 899-1
Tensile creep modulus, 1000h	1200 MPa	ISO 899-1
Charpy impact strength, 23 °C	150 kJ/m ²	ISO 179/1eU
Charpy impact strength, -30 °C	130 kJ/m ²	ISO 179/1eU
Charpy notched impact strength, 23 °C	6 kJ/m ²	ISO 179/1eA
Charpy notched impact strength, -30 °C	5 kJ/m ²	ISO 179/1eA
Ball indentation hardness, H 358/30	140 MPa	ISO 2039-1
Poisson's ratio	0.38 ^[C]	
[C]: Calculated		

Thermal properties

Melting temperature, 10 °C/min	166 °C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	88 °C	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	110 E-6/K	ISO 11359-1/-2

Flammability

Burning Behav. at 1.5mm nom. thickn.	HB class	IEC 60695-11-10
Thickness tested	1.5 mm	IEC 60695-11-10
Burning Behav. at thickness h	HB class	IEC 60695-11-10
Thickness tested	3 mm	IEC 60695-11-10
UL recognition	yes	UL 94

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Electrical properties

Relative permittivity, 100Hz	3.8	IEC 62631-2-1
Relative permittivity, 1MHz	3.8	IEC 62631-2-1
Dissipation factor, 100Hz	20 E-4	IEC 62631-2-1
Dissipation factor, 1MHz	50 E-4	IEC 62631-2-1
Volume resistivity	1E12 Ohm.m	IEC 62631-3-1
Surface resistivity	1E14 Ohm	IEC 62631-3-2
Electric strength	35 kV/mm	IEC 60243-1
Comparative tracking index	600	IEC 60112

Physical/Other properties

Humidity absorption, 2mm	0.2 %	Sim. to ISO 62
Water absorption, 2mm	0.65 %	Sim. to ISO 62
Density	1370 kg/m³	ISO 1183

Injection

Drying Recommended	no
Drying Temperature	100 °C
Drying Time, Dehumidified Dryer	3 - 4 h
Processing Moisture Content	≤0.2 %
Melt Temperature Optimum	200 °C
Min. melt temperature	190 °C
Max. melt temperature	210 °C
Screw tangential speed	≤0.3 m/s
Mold Temperature Optimum	100 °C
Min. mould temperature	80 °C
Max. mould temperature	120 °C
Hold pressure range	60 - 120 MPa
Back pressure	2 MPa
Ejection temperature	135 °C

Characteristics

Processing	Injection Moulding, Other Extrusion
Delivery form	Pellets
Additives	Release agent
Special characteristics	Low wear / Low friction

Additional information

Injection molding

Preprocessing

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

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Max. Water content 0,2 %

Processing

Standard injection moulding machines with three phase (15 to 25 D) plasticating screws will fit.

Postprocessing

Conditioning e.g. moisturizing is not necessary.

Pre-Drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems.

Storage

The product can then be stored in standard conditions until processed.

Processing Notes

Automotive

OEM

Continental

Mercedes-Benz

STANDARD

TST N 055 54.22

DBL5404

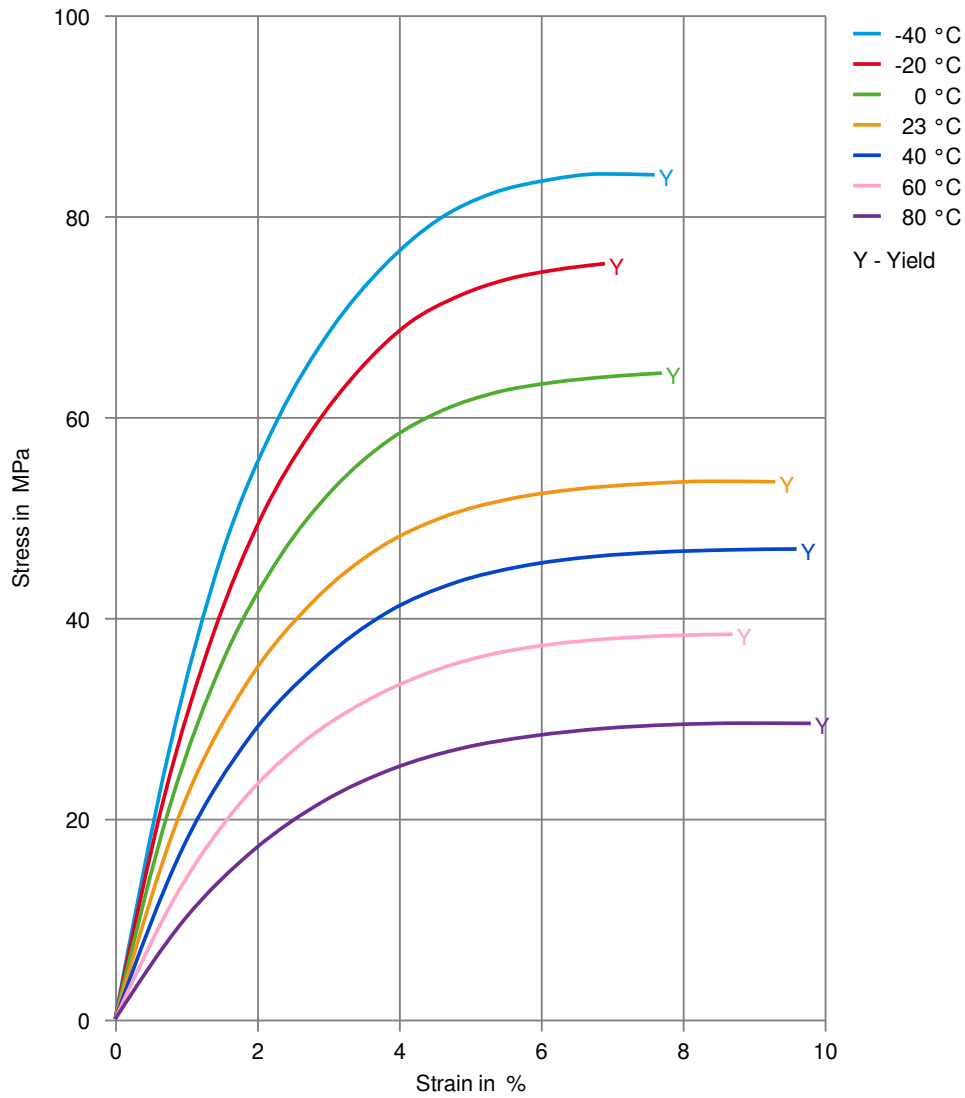
ADDITIONAL INFORMATION

BQF

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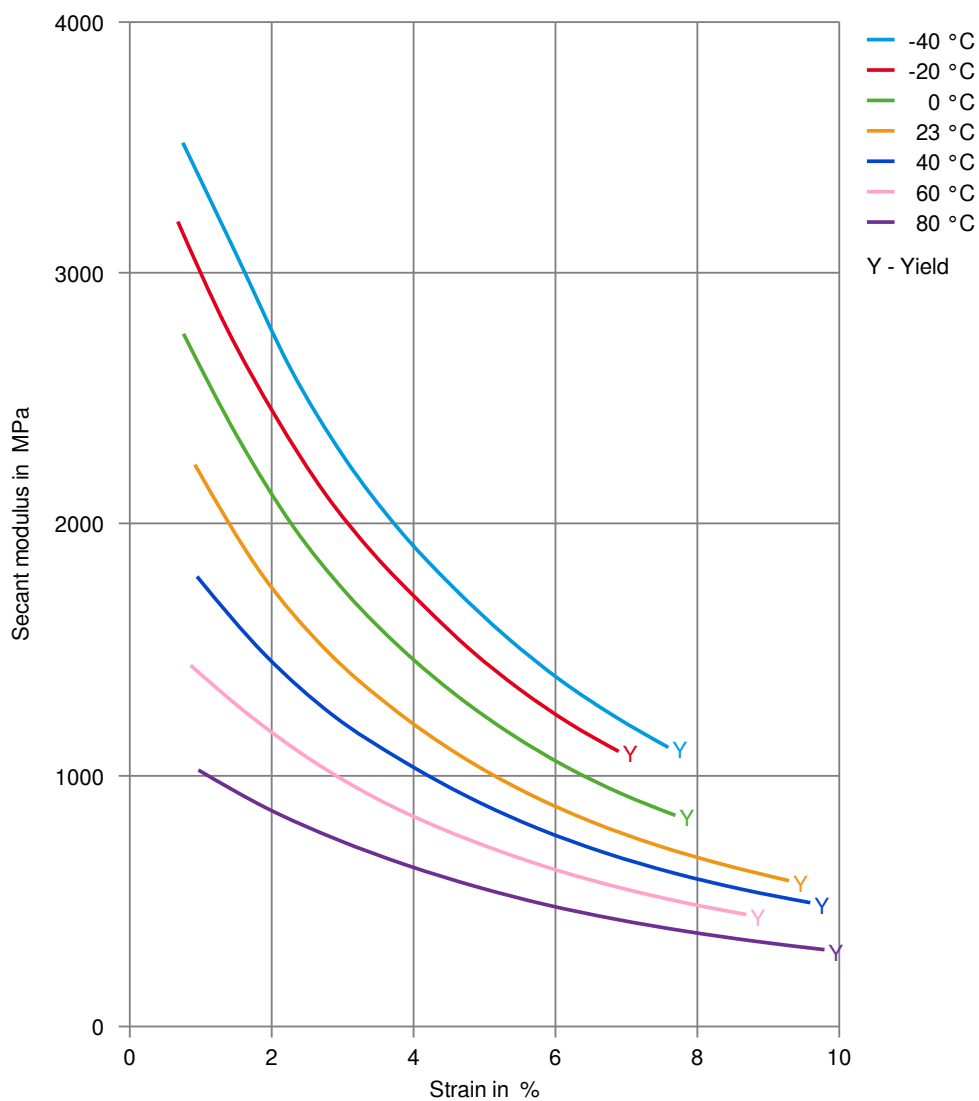
Stress-strain



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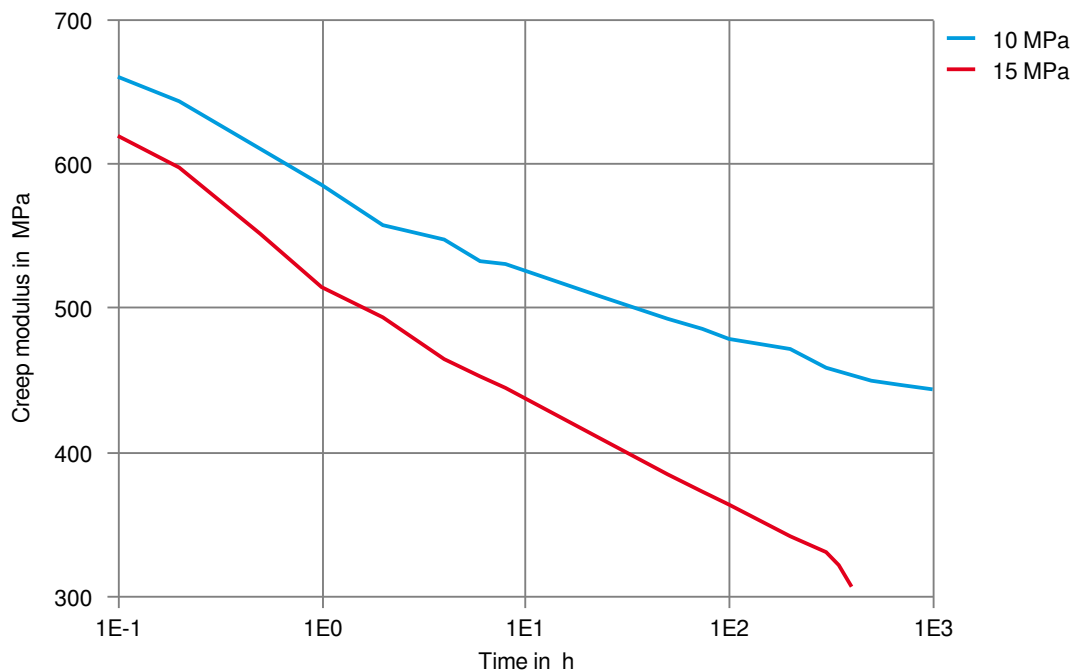
Secant modulus-strain



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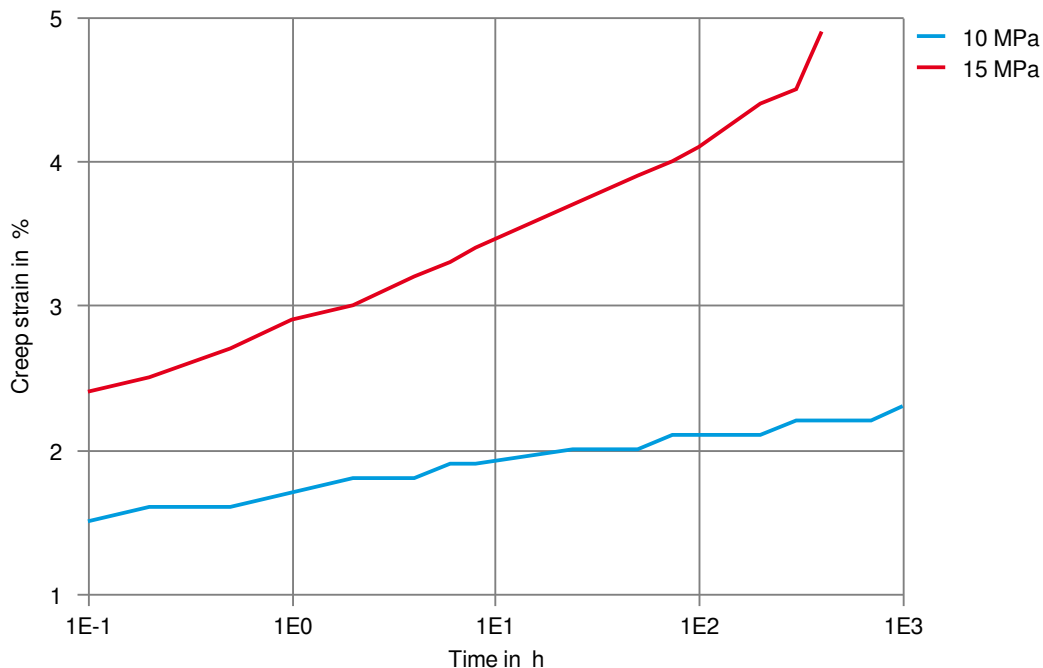
Creep modulus-time 80°C



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Creep strain-time 80 °C



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